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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	128 × 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-SOIJ
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lc671-04-sm

Email: info@E-XFL.COM

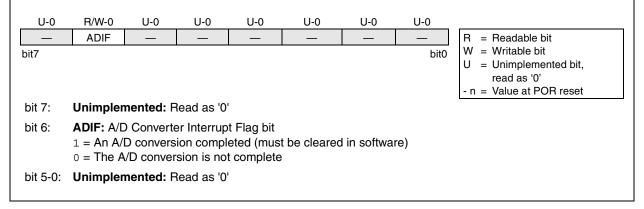
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

4.2.2.5 PIR1 REGISTER

This register contains the individual flag bits for the Peripheral interrupts.

Note: Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 4-5: PIR1 REGISTER (ADDRESS 0Ch)



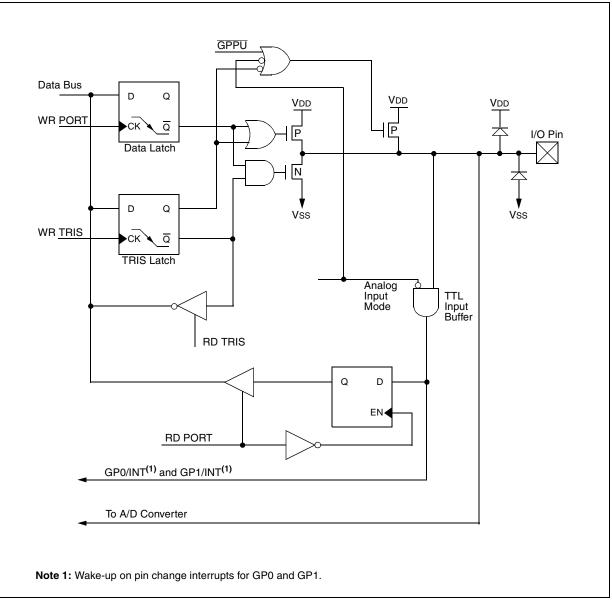


FIGURE 5-1: BLOCK DIAGRAM OF GP0/AN0 AND GP1/AN1/VREF PIN

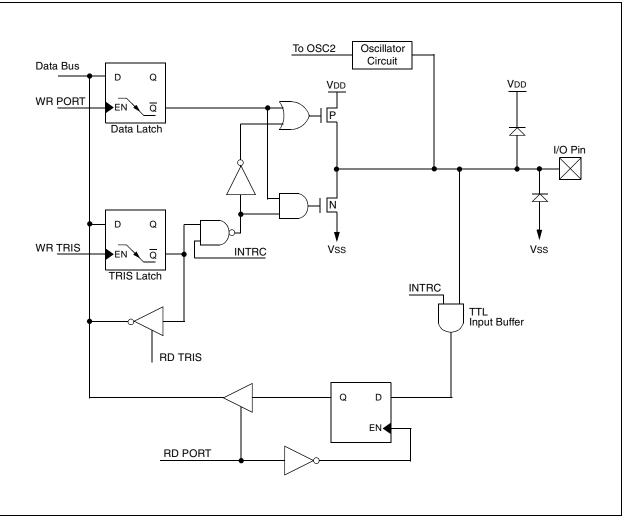


FIGURE 5-5: BLOCK DIAGRAM OF GP5/OSC1/CLKIN PIN



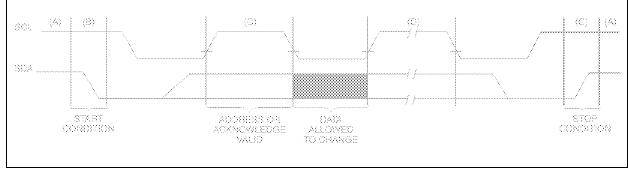
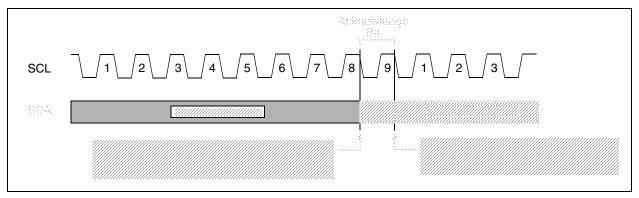


FIGURE 6-4: ACKNOWLEDGE TIMING

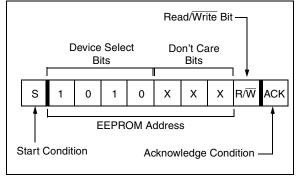


6.2 Device Addressing

After generating a START condition, the processor transmits a control byte consisting of a EEPROM address and a Read/Write bit that indicates what type of operation is to be performed. The EEPROM address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one, a read operation is selected, and when set to a zero, a write operation is selected (Figure 6-5). The bus is monitored for its corresponding EEPROM address all the time. It generates an acknowledge bit if the EEPROM address was true and it is not in a programming mode.





7.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 7-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing bit TOCS (OPTION<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If the TMR0 register is written, the increment is inhibited for the following two instruction cycles (Figure 7-2 and Figure 7-3). The user can work around this by writing an adjusted value to the TMR0 register.

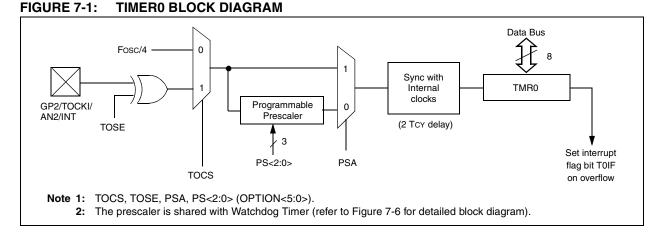
Counter mode is selected by setting bit TOCS (OPTION<5>). In counter mode, Timer0 will increment either on every rising or falling edge of pin RA4/TOCKI. The incrementing edge is determined by the bit TOSE

(OPTION<4>). Clearing bit T0SE selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 7.2.

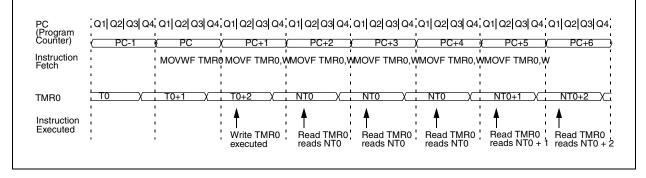
The prescaler is mutually exclusively shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by control bit PSA (OPTION<3>). Clearing bit PSA will assign the prescaler to the Timer0 module. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable. Section 7.3 details the operation of the prescaler.

7.1 <u>Timer0 Interrupt</u>

The TMR0 interrupt is generated when the TMR0 register overflows from FFh to 00h. This overflow sets bit T0IF (INTCON<2>). The interrupt can be masked by clearing bit T0IE (INTCON<5>). Bit T0IF must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The TMR0 interrupt cannot awaken the processor from SLEEP, since the timer is shut off during SLEEP. See Figure 7-4 for Timer0 interrupt timing.







8.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-To-Digital (A/D) converter module has four analog inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (VDD) or the voltage level on the GP1/AN1/VREF pin. The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode.

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

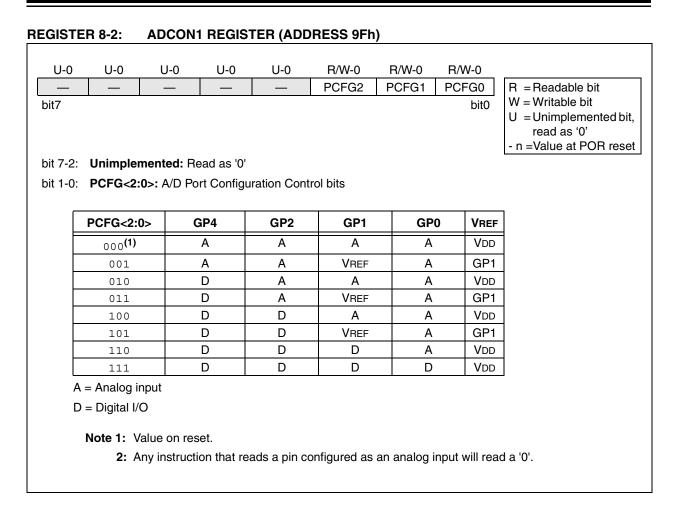
The ADCON0 Register, shown in Figure 8-1, controls the operation of the A/D module. The ADCON1 Register, shown in Figure 8-2, configures the functions of the port pins. The port pins can be configured as analog inputs (GP1 can also be a voltage reference) or as digital I/O.

- Note 1: If the port pins are configured as analog inputs (reset condition), reading the port (MOVF GPIO,W) results in reading '0's.
 - 2: Changing ADCON1 Register can cause the GPIF and INTF flags to be set in the INTCON Register. These interrupts should be disabled prior to modifying ADCON1.

R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 ADCS1 ADCS0 CHS1 CHS0 GO/DONE ADON R = Readable bit reserved reserved W = Writable bit bit0 bit7 U = Unimplemented bit, read as '0' n = Value at POR reset bit 7-6: ADCS<1:0>: A/D Conversion Clock Select bits 00 = Fosc/201 = Fosc/810 = Fosc/3211 = FRC (clock derived from an RC oscillation) Reserved bit 5: bit 4-3: CHS<1:0>: Analog Channel Select bits 00 = channel 0, (GP0/AN0) 01 = channel 1, (GP1/AN1) 10 = channel 2, (GP2/AN2) 11 = channel 3, (GP4/AN3) GO/DONE: A/D Conversion Status bit bit 2: If ADON = 11 = A/D conversion in progress (setting this bit starts the A/D conversion) 0 = A/D conversion not in progress (this bit is automatically cleared by hardware when the A/D conversion is complete) bit 1: Reserved bit 0: ADON: A/D on bit 1 = A/D converter module is operating 0 = A/D converter module is shut off and consumes no operating current

REGISTER 8-1: ADCON0 REGISTER (ADDRESS 1Fh)

PIC12C67X



The ADRES Register contains the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRES register, the GO/DONE bit (ADCON0<2>) is cleared, and A/D interrupt flag bit ADIF (PIE1<6>) is set. The block diagrams of the A/D module are shown in Figure 8-1.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine sample time, see Section 8.1. After this acquisition time has elapsed, the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

- 1. Configure the A/D module:
 - Configure analog pins / voltage reference / and digital I/O (ADCON1 and TRIS)
 - Select A/D input channel (ADCON0)
 - Select A/D conversion clock (ADCON0)
 - Turn on A/D module (ADCON0)

- 2. Configure A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set GIE bit
- 3. Wait the required acquisition time.
- 4. Start conversion:
 - Set GO/DONE bit (ADCON0)
- 5. Wait for A/D conversion to complete, by either:Polling for the GO/DONE bit to be cleared
 - OR
 - Waiting for the A/D interrupt
- 6. Read A/D Result Register (ADRES), clear bit ADIF if required.
- 7. For the next conversion, go to step 1, step 2 or step 3 as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before next acquisition starts.

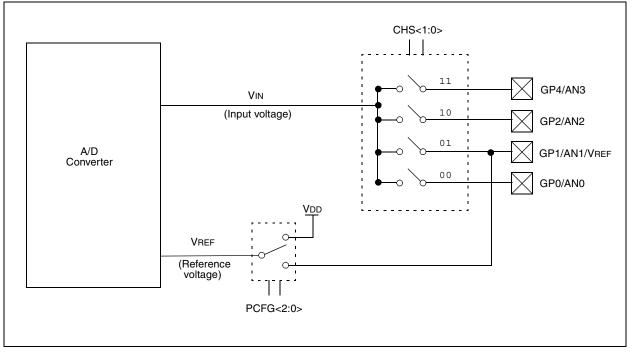


FIGURE 8-1: A/D BLOCK DIAGRAM

9.4 <u>Power-on Reset (POR), Power-up</u> <u>Timer (PWRT) and Oscillator Start-up</u> <u>Timer (OST)</u>

9.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create a Poweron Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting.*"

9.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature and process variation. See Table 11-4.

9.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

9.4.4 TIME-OUT SEQUENCE

On power-up, the Time-out Sequence is as follows: first, PWRT time-out is invoked after the POR time delay has expired; then, OST is activated. The total time-out will vary, based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 9-7, Figure 9-8, and Figure 9-9 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (Figure 9-9). This is useful for testing purposes or to synchronize more than one PIC12C67X device operating in parallel.

9.4.5 POWER CONTROL (PCON)/STATUS REGISTER

The Power Control/Status Register, PCON (address 8Eh), has one bit. See Register 4-6 for register.

Bit1 is POR (Power-on Reset). It is cleared on a Poweron Reset and is unaffected otherwise. The user sets this bit following a Power-on Reset. On subsequent resets, if POR is '0', it will indicate that a Power-on Reset must have occurred.

Oscillator Configuration	Power	Wake-up from SLEEP	
	PWRTE = 0	PWRTE = 1	
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	1024Tosc
INTRC, EXTRC	72 ms	_	—

TABLE 9-4: TIME-OUT IN VARIOUS SITUATIONS

TABLE 9-5: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	то	PD	
0	1	1	Power-on Reset
0	0	х	Illegal, TO is set on POR
0	x	0	Illegal, PD is set on POR
1	0	u	WDT Reset
1	0	0	WDT Wake-up
1	u	u	MCLR Reset during normal operation
1	1	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP

Legend: u = unchanged, x = unknown.

9.8 Power-down Mode (SLEEP)

Power-down mode is entered by executing a $\ensuremath{\mathtt{SLEEP}}$ instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the \overline{PD} bit (STATUS<3>) is cleared, the \overline{TO} (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before the SLEEP instruction was executed (driving high, low or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD or Vss, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D, and disable external clocks. Pull all I/O pins that are hi-impedance inputs, high or low externally, to avoid switching currents caused by floating inputs. The TOCKI input, if enabled, should also be at VDD or Vss for lowest current consumption. The contribution from on-chip pull-ups on GPIO should be considered.

The $\overline{\text{MCLR}}$ pin, if enabled, must be at a logic high level (VIHMC).

9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- 1. External reset input on MCLR pin.
- 2. Watchdog Timer Wake-up (if WDT was enabled).
- 3. GP2/INT interrupt, interrupt GPIO port change or some Peripheral Interrupts.

External MCLR Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The TO and PD bits in the STATUS register can be used to determine the cause of device reset. The PD bit, which is set on power-up, is cleared when SLEEP is invoked. The TO bit is cleared if a WDT time-out occurred (and caused wake-up).

The following peripheral interrupt can wake the device from SLEEP:

1. A/D conversion (when A/D clock source is RC).

Other peripherals can not generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

9.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs before the the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the TO bit will not be set and PD bits will not be cleared.
- If the interrupt occurs during or after the execution of a SLEEP instruction, the device will immediately wake-up from sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the PD bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the \overline{PD} bit. If the \overline{PD} bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

FIGURE 9-16: WAKE-UP FROM SLEEP THROUGH INTERRUPT

; a1 a2 a3 a osc1 ///////	4; Q1 Q2 Q3 Q4 _/~~~~		Q1 Q2 Q3 Q4	01 02 03 04 ////////	01 02 03 04	Q1 Q2 Q3 Q4;
CLKOUT(4)	-∖/	Tost(2)	/	\/	\/¦	
GPIO pin	 	x		I I I		
GPIF flag (INTCON<0>)				Interrupt Latency (Note 3)		i
GIE bit (INTCON<7>)	 	Processor in SLEEP				
INSTRUCTION FLOW	1			i i		1
РС Х РС	X PC+1	X PC+2	PC+2	X PC + 2	X 0004h	0005h
Instruction fetched Inst(PC) = SLEEF	Inst(PC + 1)	I I I	Inst(PC + 2)	I I I	Inst(0004h)	Inst(0005h)
Instruction executed Inst(PC - 1)	SLEEP	I i	Inst(PC + 1)	Dummy cycle	Dummy cycle	Inst(0004h)

Note 1: XT, HS or LP oscillator mode assumed.

- 2: TOST = 1024TOSC (drawing not to scale) This delay will not be there for INTRC and EXTRC osc mode.
- **3:** GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
- 4: CLKOUT is not available in XT, HS or LP osc modes, but shown here for timing reference.

9.9 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note:	Microchip does not recommend code pro-
	tecting windowed devices.

9.10 ID Locations

Four memory locations (2000h - 2003h) are designated as ID locations, where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution, but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

9.11 In-Circuit Serial Programming

PIC12C67X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the GP1 and GP0 pins low, while raising the $\overline{\text{MCLR}}$ (VPP) pin from VIL to VIHH (see programming specification). GP1 (clock) becomes the programming clock and GP0 (data) becomes the programming data. Both GP0 and GP1 are Schmitt Trigger inputs in this mode.

After reset, and if the device is placed into programming/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC12C67X Programming Specifications.

FIGURE 9-17: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION

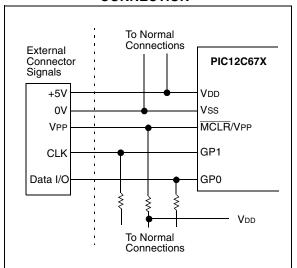


TABLE 10-2: INSTRUCTION SET S

· ·		Description	Cycles	14-Bit Opcode		Status	Notes		
Operands				MSb			LSb	Affected	
BYTE-ORIE		FILE REGISTER OPERATIONS							
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0000	0011	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff		Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100		ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	00	0010		ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIEN	TED FIL	E REGISTER OPERATIONS							
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL A	ND CO	NTROL OPERATIONS							
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (i.e., MOVF PORTE, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

SUBLW	Subtract W from Literal	SUBWF	Subtract W from f
Syntax:	[<i>label</i>] SUBLW k	Syntax:	[<i>label</i>] SUBWF f,d
Operands:	$0 \leq k \leq 255$	Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	$k - (W) \to (W)$	Operation:	(f) - (W) → (dest)
Status	C, DC, Z	-	
Affected:		Status Affected:	C, DC, Z
Encoding:	11 110x kkkk kkkk	Encoding:	00 0010 dfff ffff
Description:	The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.	Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in regis-
Words:	1		ter 'f'.
Cycles:	1	Words:	1
Example 1:	SUBLW 0x02	Cycles:	1
	Before Instruction	Example 1:	SUBWF REG1,1
	W = 1 $C = ?$		Before Instruction
	After Instruction		REG1 = 3
	W = 1		W = 2 C = ?
	C = 1; result is positive		After Instruction
Example 2:	Before Instruction		REG1 = 1
	W = 2		W = 2
	C = ?		C = 1; result is positive
	After Instruction	Example 2:	Before Instruction
	W = 0 C = 1; result is zero		REG1 = 2 W = 2
Example 2:	Before Instruction		C = ?
Example 3:			After Instruction
	W = 3 C = ?		REG1 = 0
	After Instruction		W = 2 C = 1; result is zero
	W = 0xFF	Example 3:	Before Instruction
	C = 0; result is nega-	Example 3.	REG1 = 1
	tive		W = 2
			C = ?
			After Instruction
			REG1 = 0xFF W = 2

W	=	2
С	=	0; result is negative

SWAPF	Swap Ni	bbles in	f	
Syntax:	[<i>label</i>] SWAPF f,d			
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]			
Operation:	(f<3:0>) - (f<7:4>) -			
Status Affected:	None			
Encoding:	00	1110	dfff	ffff
Description:	The upper register 'f 0, the resident of the ter. If 'd' is register 'f	" are excl sult is places a 1, the re	nanged. ced in V	. If 'd' is V regis-
Words:	1			
Cycles:	1			
Example	SWAPF	REG,	0	
	Before In	struction		
		REG1	= 0	xA5
	After Inst	ruction		
		REG1 W	-	xA5 x5A

XORLW	Exclusive OR Literal with W			
Syntax:	[<i>label</i>] XORLW k			
Operands:	$0 \le k \le 255$			
Operation:	(W) .XOR. $k \rightarrow (W)$			
Status Affected:	Z			
Encoding:	11 1010 kkkk kkkk			
Description:	The contents of the W register are XOR'ed with the eight bit lit- eral 'k'. The result is placed in the W register.			
Words:	1			
Cycles:	1			
Example:	XORLW 0xAF			
	Before Instruction			
	W = 0xB5			
	After Instruction			
	W = 0x1A			

TRIS	Load TRI	S Regis	ster					
Syntax:	[label]	TRIS	f					
Operands:	$5 \leq f \leq 7$							
Operation:	(W) \rightarrow TRIS register f;							
Status Affected:	None							
Encoding:	00	0000	0110	Offf				
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writ- able, the user can directly address them.							
Words:	1							
Cycles:	1							
Example								
	To maintain upward compatibility with future PIC12C67X products, do not use this instruction.							

XORWF	Exclusive OR W with f								
Syntax:	[label]	XORWF	f,d						
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$								
Operation:	(W) .XOF	$R.\;(f)\to($	dest)						
Status Affected:	Z								
Encoding:	0 0	0110	dff:	f	ffff				
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.								
Words:	1								
Cycles:	1								
Example	XORWF	REG	1						
	Before In	struction	I						
		REG W	= =	0x/ 0xl					
	After Inst	ruction							
	REG = 0x1A W = 0xB5								

12.4 DC CHARACTERISTICS:

PIC12LC671/672 (Commercial, Industrial) PIC12LCE673/674 (Commercial, Industrial)

DC CHA	RACTERISTICS	Standard Operating Conditions (unless otherwise specified)Operating temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial) $-40^{\circ}C \le TA \le +85^{\circ}C$ (industrial)Operating voltage VDD range as described in DC spec Section 12.1 and								
		Section 12.2.								
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions			
	Input Low Voltage									
	I/O ports	VIL								
D030	with TTL buffer		Vss	—	0.8V	V	For $4.5V \le VDD \le 5.5V$			
			Vss	—	0.15VDD	V	otherwise			
D031	with Schmitt Trigger buffer		Vss	—	0.2Vdd	V				
D032	MCLR, GP2/T0CKI/AN2/INT		Vss		0.2Vdd	V				
	(in EXTRC mode)									
D033	OSC1 (in EXTRC mode)		Vss	—	0.2VDD	V	Note 1			
D033	OSC1 (in XT, HS, and LP)		Vss	—	0.3VDD	V	Note 1			
	Input High Voltage									
	I/O ports	Vін		—						
D040	with TTL buffer		2.0V	—	Vdd	V	$4.5V \le VDD \le 5.5V$			
D040A			0.25VDD + 0.8V		Vdd	V	otherwise			
D041	with Schmitt Trigger buffer		0.8VDD	—	Vdd	V	For entire VDD range			
D042	MCLR, GP2/T0CKI/AN2/INT		0.8VDD	—	Vdd	V	_			
D042A	OSC1 (XT, HS, and LP)		0.7VDD	_	Vdd	v	Note 1			
D043	OSC1 (in EXTRC mode)		0.9VDD	_	Vdd	v				
	Input Leakage Current (Notes 2, 3)									
D060	I/O ports	lı∟	_	_	<u>+</u> 1	μA	$Vss \le VPIN \le VDD$, Pin at hi-impedance			
D061	GP3/MCLR (Note 5)				<u>+</u> 30	μA	$Vss \leq VPIN \leq VDD$			
D061A	GP3 (Note 6)				<u>+</u> 5	μA	$Vss \leq VPIN \leq VDD$			
D062	GP2/T0CKI		_		<u>+</u> 5	μA	$Vss \leq VPIN \leq VDD$			
D063	OSC1		—	_	<u>+</u> 5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP osc configuration			
D070	GPIO weak pull-up current (Note 4)	IPUR	50	250	400	μA	VDD = 5V, VPIN = VSS			
	MCLR pull-up current	—	_	—	30	μA	VDD = 5V, VPIN = VSS			
	Output Low Voltage	1								
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, −40°C to +85°C			
D080A			-	_	0.6	V	IOL = 7.0 mA, VDD = 4.5V, −40°C to +125°C			
D083	OSC2/CLKOUT		-	_	0.6	V	IOL = TBD, VDD = 4.5V, −40°C to +85°C			
D083A			_		0.6	V	IOL = TBD, VDD = 4.5V, −40°C to +125°C			

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C67X be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: Does not include GP3. For GP3 see parameters D061 and D061A.

5: This spec. applies to GP3/MCLR configured as external MCLR and GP3/MCLR configured as input with internal pull-up enabled.

6: This spec. applies when GP3/MCLR is configured as an input with pull-up disabled. The leakage current of the MCLR circuit is higher than the standard I/O logic.

FIGURE 12-6: CLKOUT AND I/O TIMING

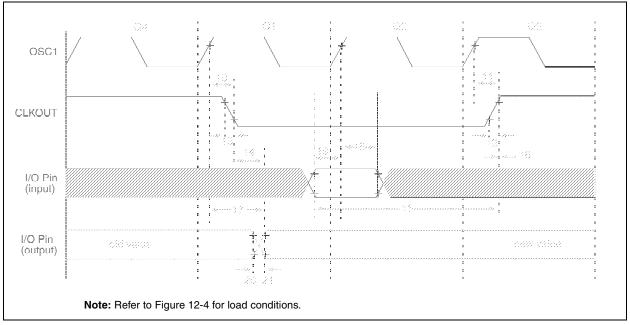


TABLE 12-3:	CLKOUT AND I/O TIMING REQUIREMENTS
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Param No.	Sym	Characteristic		Min	Тур†	Мах	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		_	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		_	75	200	ns	Note 1
12*	TckR	CLKOUT rise time	_	35	100	ns	Note 1	
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		—	_	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOU	Т↑	Tosc + 200	—	—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT	↑	0	_	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port c	OSC1↑ (Q1 cycle) to Port out valid		50	150	ns	
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Port	PIC12 C 67X	100	_	—	ns	
18A*		input invalid (I/O in hold time)	PIC12 LC 67X	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I time)	/O in setup	0	—	—	ns	
20*	TioR	Port output rise time	PIC12 C 67X	—	10	40	ns	
20A*			PIC12 LC 67X	—		80	ns	
21*	TioF	Port output fall time	PIC12 C 67X	—	10	40	ns	
21A*			PIC12 LC 67X	_		80	ns	
22††*	Tinp	GP2/INT pin high or low tim	e	Тсү	—	—	ns	
23††*	Trbp	GP0/GP1/GP3 change INT time	high or low	Тсү	—	_	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

t These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in EXTRC and INTRC modes where CLKOUT output is 4 x Tosc.

TABLE 12-7:A/D CONVERTER CHARACTERISTICS:
PIC12C671/672-04/PIC12CE673/674-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC12C671/672-10/PIC12CE673/674-10 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC12LC671/672-04/PIC12LCE673/674-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
A01	NR	Resolution		_	_	8-bits	bit	VREF = VDD = 5.12V, $VSS \le VAIN \le VREF$
A02	Eabs	Total absolute error		_	_	< ±1	LSb	VREF = VDD = 5.12V, VSS \leq VAIN \leq VREF
A03	EIL	Integral linearity er	ror	_	—	< ±1	LSb	$\label{eq:VREF} \begin{array}{l} VREF = VDD = 5.12V,\\ VSS \leq VAIN \leq VREF \end{array}$
A04	Edl	Differential linearity	/ error	_	_	< ±1	LSb	VREF = VDD = 5.12V, $VSS \le VAIN \le VREF$
A05	EFS	Full scale error		_	_	< ±1	LSb	$\begin{array}{l} VREF=VDD=5.12V,\\ VSS\leqVAIN\leqVREF \end{array}$
A06	EOFF	Offset error		—	_	< ±1	LSb	$\begin{array}{l} VREF=VDD=5.12V,\\ VSS\leqVAIN\leqVREF \end{array}$
A10	_	Monotonicity		_	guaranteed (Note 3)	—	—	$Vss \leq Vain \leq Vref$
A20	VREF	Reference voltage		2.5V	_	VDD + 0.3	V	
A25	VAIN	Analog input voltag	je	Vss - 0.3	_	VREF + 0.3	V	
A30	ZAIN	Recommended im analog voltage sou		_	_	10.0	kΩ	
A40	IAD	A/D conversion	PIC12 C 67X	_	180	—	μA	Average current con-
		current (VDD)	PIC12LC67X	_	90	—	μA	sumption when A/D is on. (Note 1)
A50	IREF	VREF input current	(Note 2)	10	_	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 8.1.
					10	μA	During A/D Conversion cycle	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from GP1 pin or VDD pin, whichever is selected as reference input.

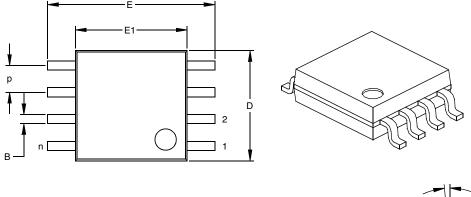
3: The A/D conversion result never decreases with an increase in the Input Voltage, and has no missing codes.

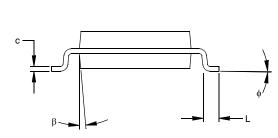
PIC12C67X

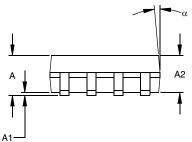
NOTES:

8-Lead Plastic Small Outline (SM) – Medium, 208 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







	Units		INCHES*		MILLIMETERS			
Dimensio	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		8			8		
Pitch	р		.050			1.27		
Overall Height	А	.070	.075	.080	1.78	1.97	2.03	
Molded Package Thickness	A2	.069	.074	.078	1.75	1.88	1.98	
Standoff	A1	.002	.005	.010	0.05	0.13	0.25	
Overall Width	Е	.300	.313	.325	7.62	7.95	8.26	
Molded Package Width	E1	.201	.208	.212	5.11	5.28	5.38	
Overall Length	D	.202	.205	.210	5.13	5.21	5.33	
Foot Length	L	.020	.025	.030	0.51	0.64	0.76	
Foot Angle	¢	0	4	8	0	4	8	
Lead Thickness	С	.008	.009	.010	0.20	0.23	0.25	
Lead Width	В	.014	.017	.020	0.36	0.43	0.51	
Mold Draft Angle Top	α	0	12	15	0	12	15	
Mold Draft Angle Bottom	β	0	12	15	0	12	15	

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

Drawing No. C04-056

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